

## General Description

These dual N Channel enhancement mode power fieldeffect transistors are using trench DMOS technology.

This advanced technology has been especially tailoredto minimize on-state resistance, provide superior switching performance, and withstand high energypulse in the avalanche and commutation mode. Thesedevices are well suited for high efficiency fast switchingapplications.

## Features

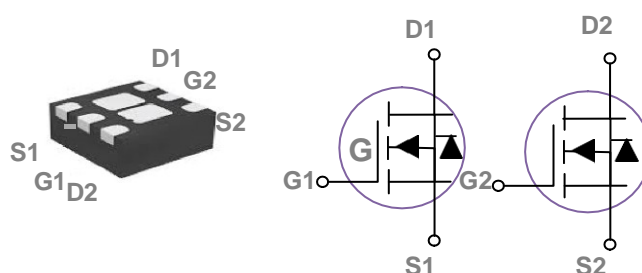
- Fast switching
- Green Device Available
- Suit for 1.8V Gate Drive Applications
- Marking : WA

## Applications

- Notebook
- Load Switch
- Networking
- Hand-held Instruments

BVDSS	RDSON	ID
20V	22mΩ	6.5A

## DFN2X2 Dual 2EP Pin Configuration



## Absolute Maximum Ratings $T_c=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	20	V
$V_{GS}$	Gate-Source Voltage	$\pm 12$	V
$I_D$	Drain Current - Continuous ( $T_c=25^{\circ}\text{C}$ )	6.5	A
	Drain Current - Continuous ( $T_c=100^{\circ}\text{C}$ )	4.3	A
$I_{DM}$	Drain Current - Pulsed <sub>r</sub>	20.8	A
$P_D$	Power Dissipation ( $T_c=25^{\circ}\text{C}$ )	1.78	W
	Power Dissipation - Derate above $25^{\circ}\text{C}$	0.02	W/ $^{\circ}\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^{\circ}\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^{\circ}\text{C}$

## Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to Ambient		100	$^{\circ}\text{C}/\text{W}$

## Electrical Characteristics ( $T_J=25\text{ }^\circ\text{C}$ , unless otherwise) noted)

### Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	20			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	$BV_{DSS}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$		0.02		$V/^\circ\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=20V, V_{GS}=0V, T_J=25^\circ\text{C}$			1	$\mu\text{A}$
		$V_{DS}=16V, V_{GS}=0V, T_J=125^\circ\text{C}$			10	$\mu\text{A}$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 10V, V_{DS}=0V$			$\pm 100$	nA

### On Characteristics

$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=4.5V, I_D=3A$		22	25	$\text{m}\Omega$
		$V_{GS}=2.5V, I_D=2A$		26	30	$\text{m}\Omega$
		$V_{GS}=1.8V, I_D=1.5A$		40	45	$\text{m}\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	0.3	0.6	1	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	$V_{GS(th)}$ Temperature Coefficient			-2		$\text{mV}/^\circ\text{C}$
$g_{fs}$	Forward Transconductance	$V_{DS}=10V, I_D=2A$		4.4		S

### Dynamic and switching Characteristics

$Q_g$	Total Gate Charge <sub>2,3</sub>	$V_{DS}=10V, V_{GS}=4.5V, I_D=3A$		5.8	10	nC
$Q_{gs}$	Gate-Source Charge <sub>2,3</sub>			0.6	1.5	
$Q_{gd}$	Gate-Drain Charge <sub>2,3</sub>			1.5	3	
$T_{d(on)}$	Turn-On Delay Time <sub>2,3</sub>	$V_{DD}=10V, V_{GS}=4.5V, R_G=25$ $I_D=1A$	---	2.9	6	ns
$T_r$	Rise Time <sub>2,3</sub>			8.4	16	
$T_{d(off)}$	Turn-Off Delay Time <sub>2,3</sub>			19.2	38	
$T_f$	Fall Time <sub>2,3</sub>			5.6	12	
$C_{iss}$	Input Capacitance	$V_{DS}=15V, V_{GS}=0V, F=1\text{MHz}$		315	600	pF
$C_{oss}$	Output Capacitance		---	50	80	
$C_{rss}$	Reverse Transfer Capacitance			40	60	

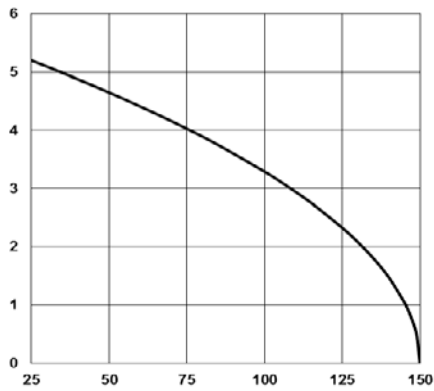
### Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current	$V_G=V_D=0V$ , Force Current			3.8	A
$I_{SM}$	Pulsed Source Current				7.6	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$			1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.

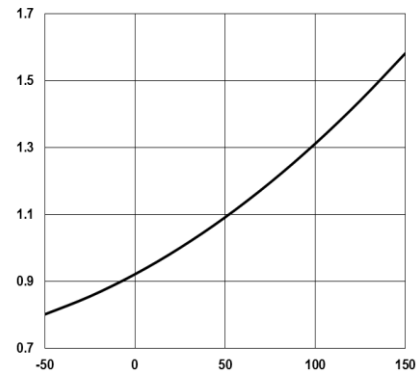
$I_D$ , Continuous Drain Current (A)



$T_C$ , Case Temperature ( $^{\circ}C$ )

Fig.1 Continuous Drain Current vs.  $T_C$

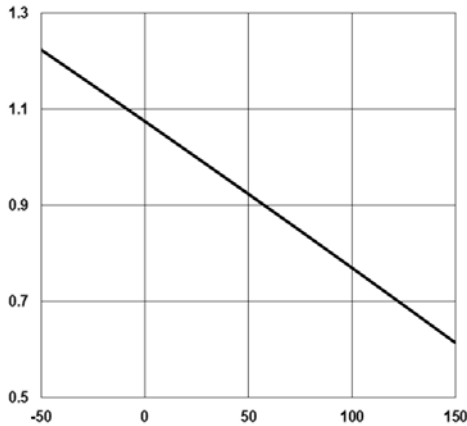
Normalized On Resistance (m)



$T_J$ , Junction Temperature ( $^{\circ}C$ )

Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_J$

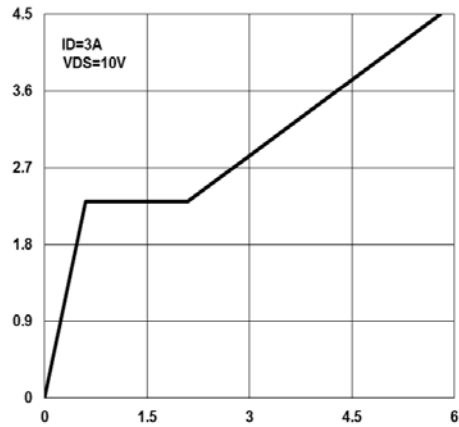
Normalized Gate Threshold Voltage (V)



$T_J$ , Junction Temperature ( $^{\circ}C$ )

Fig.3 Normalized  $V_{th}$  vs.  $T_J$

$V_{GS}$ , Gate to Source Voltage (V)



$Q_g$ , Gate Charge (nC)

Fig.4 Gate Charge Waveform

Normalized Thermal Response ( $R_{\theta JA}$ )

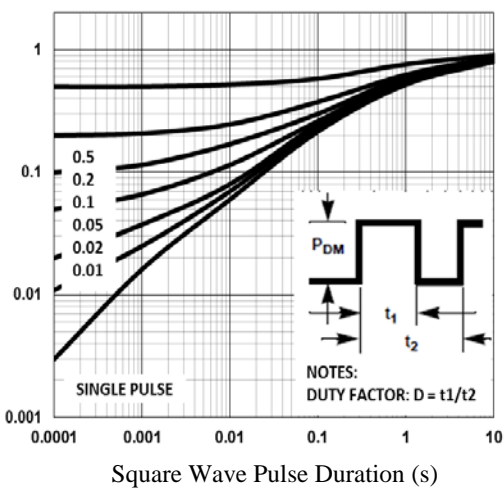


Fig.5 Normalized Transient Impedance

$I_D$ , Continuous Drain Current (A)

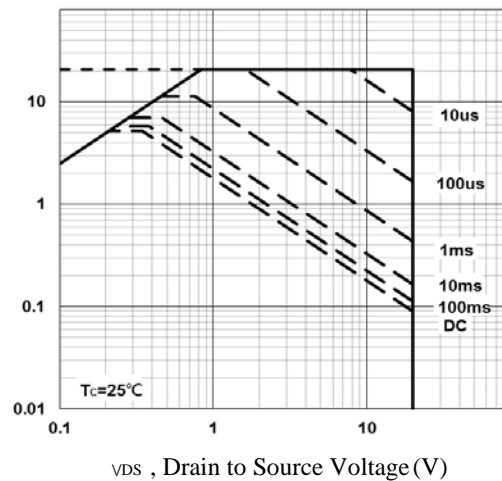


Fig.6 Maximum Safe Operation Area

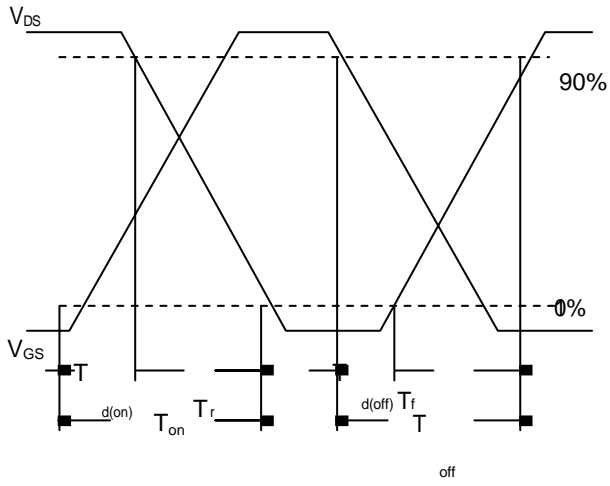


Fig.7 Switching Time Waveform

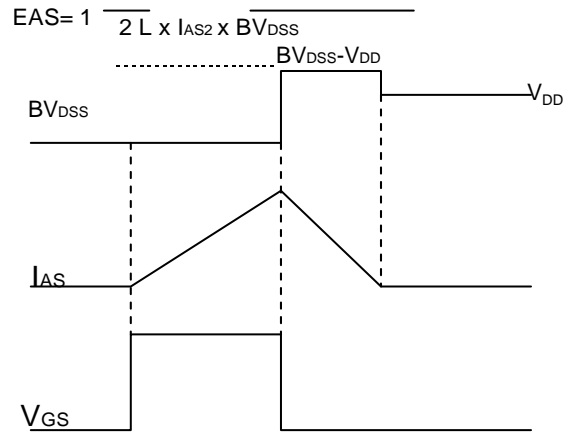
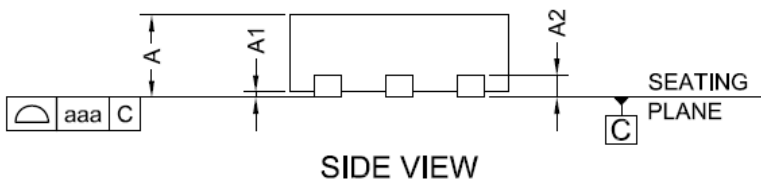
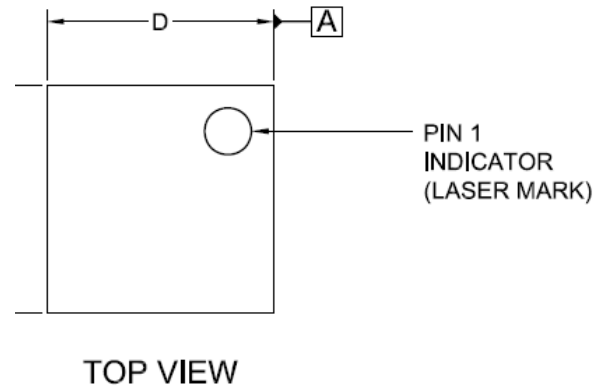
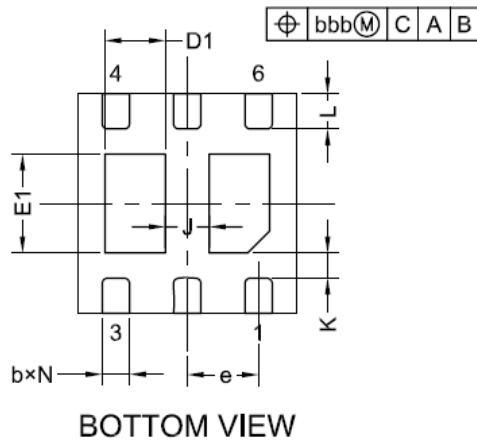


Fig.8 EAS Waveform

## PPAK2X2 Dual 2EP PACKAGE INFORMATION



COMMON DIMENSIONS  
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	TYP	MAX
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A2	0.203		
b	0.20	0.25	0.30
D	1.95	2.00	2.05
D1	0.50	0.55	0.60
E	1.95	2.00	2.05
E1	0.85	0.90	0.95
e	0.65BSC		
L	0.27	0.32	0.37
J	0.40BSC		
K	0.20MIN		
N	6		
aaa	0.08		
bbb	0.10		

## X-ON Electronics

Largest Supplier of Electrical and Electronic Components

*Click to view similar products for [MOSFET](#) category:*

*Click to view products by [Shikues](#) manufacturer:*

Other Similar products are found below :

[IRFD120](#) [JANTX2N5237](#) [BUK455-60A/B](#) [MIC4420CM-TR](#) [VN1206L](#) [NDP4060](#) [SI4482DY](#) [IPS70R2K0CEAKMA1](#) [SQD23N06-31L-GE3](#)  
[TK16J60W,S1VQ\(O](#) [2SK2614\(TE16L1,Q\)](#) [DMN1017UCP3-7](#) [DMN1053UCP4-7](#) [SQJ469EP-T1-GE3](#) [NTE2384](#) [DMC2700UDMQ-7](#)  
[DMN2080UCB4-7](#) [DMN61D9UWQ-13](#) [US6M2GTR](#) [DMN31D5UDJ-7](#) [DMP22D4UFO-7B](#) [DMN1006UCA6-7](#) [DMN16M9UCA6-7](#)  
[STF5N65M6](#) [IRF40H233XTMA1](#) [STU5N65M6](#) [DMN6022SSD-13](#) [DMN13M9UCA6-7](#) [DMTH10H4M6SPS-13](#) [DMN2990UFB-7B](#)  
[IPB80P04P405ATMA2](#) [2N7002W-G](#) [MCAC30N06Y-TP](#) [MCQ7328-TP](#) [BXP7N65D](#) [BXP4N65F](#) [AOL1454G](#) [WMJ80N60C4](#) [BXP2N20L](#)  
[BXP2N65D](#) [BXT1150N10J](#) [BXT1700P06M](#) [TSM60NB380CP ROG](#) [RQ7L055BGTCR](#) [DMNH15H110SK3-13](#) [SLF10N65ABV2](#)  
[BSO203SP](#) [BSO211P](#) [IPA60R230P6](#) [IPA60R460CE](#)